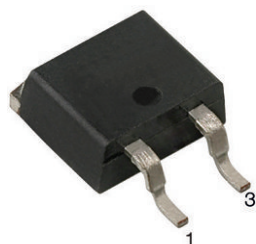
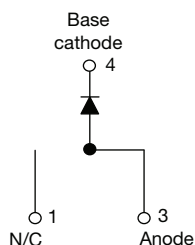


Hyperfast Rectifier, 20 A FRED Pt® G5


D²PAK 2L (TO-263AB 2L)


FEATURES

- Hyperfast and optimized Q_{rr}
- Best in class forward voltage drop and switching losses trade off
- Optimized for high speed operation
- 175 °C maximum operating junction temperature
- Polyimide passivation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- AEC-Q101 qualified meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT
HALOGEN
FREE

LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS

$I_{F(AV)}$	20 A
V_R	1200 V
V_F at I_F at 125 °C	1.88 V
t_{rr}	37 ns
T_J max.	175 °C
Package	D ² PAK 2L (TO-263AB 2L)
Circuit configuration	Single

DESCRIPTION / APPLICATIONS

Featuring a unique combination of low conduction and switching losses, this rectifier is the right choice for high frequency converters, both soft switched / resonant. Specifically designed to improve efficiency of PFC and output rectification stages of EV / HEV battery charging stations, booster stage of solar inverters and UPS applications, these devices are perfectly matched to operate with MOSFETs or high speed IGBTs.

MECHANICAL DATA

Case: D²PAK 2L (TO-263AB 2L)

Molding compound meets UL 94 V-0 flammability rating

Terminals: matte tin plated leads, solderable per J-STD-002

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Repetitive peak reverse voltage	V_{RRM}		1200	V
Average rectified forward current	$I_{F(AV)}$	$T_C = 103\text{ °C}$	20	A
Repetitive peak forward current	I_{FRM}	$T_C = 103\text{ °C}$, $D = 0.50$, $f = 20\text{ kHz}$	32	
Non-repetitive peak surge current	I_{FSM}	$T_C = 45\text{ °C}$, $t_p = 10\text{ ms}$, sine wave	125	
Operating junction and storage temperature	T_J, T_{Stg}		-55 to +175	°C

ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ °C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	$I_R = 100\text{ }\mu\text{A}$	1200	-	-	V
Forward voltage	V_F	$I_F = 20\text{ A}$	-	2.04	2.66	
		$I_F = 20\text{ A}$, $T_J = 125\text{ °C}$	-	1.88	-	
Reverse leakage current	I_R	$V_R = V_R$ rated	-	-	50	μA
		$T_J = 125\text{ °C}$, $V_R = V_R$ rated	-	-	500	
Junction capacitance	C_T	$V_R = 200\text{ V}$	-	10	-	pF
Series inductance	L_S	Measured to lead 5 mm from package body	-	8	-	nH

DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t_{rr}	$I_F = 1.0\text{ A}$, $dI_F/dt = 100\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$	-	37	-	ns
		$T_J = 25^\circ\text{C}$	-	125	-	
		$T_J = 125^\circ\text{C}$	-	188	-	
Peak recovery current	I_{RRM}	$T_J = 25^\circ\text{C}$	-	14	-	A
		$T_J = 125^\circ\text{C}$	-	19	-	
Reverse recovery charge	Q_{rr}	$T_J = 25^\circ\text{C}$	-	670	-	nC
		$T_J = 125^\circ\text{C}$	-	1450	-	
Reverse recovery time	t_{rr}	$T_J = 25^\circ\text{C}$	-	90	-	ns
		$T_J = 125^\circ\text{C}$	-	107	-	
Peak recovery current	I_{RRM}	$T_J = 25^\circ\text{C}$	-	28	-	A
		$T_J = 125^\circ\text{C}$	-	48	-	
Reverse recovery charge	Q_{rr}	$T_J = 25^\circ\text{C}$	-	1450	-	nC
		$T_J = 125^\circ\text{C}$	-	2930	-	

THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Thermal resistance, junction-to-case	R_{thJC}		-	-	1.7	$^\circ\text{C}/\text{W}$
Weight			-	2.0	-	g
			-	0.07	-	oz.
Maximum junction and storage temperature range	T_J, T_{stg}		-55	-	175	$^\circ\text{C}$
Marking device		Case style D ² PAK 2L (TO-263AB 2L)	E5TH2112SH			

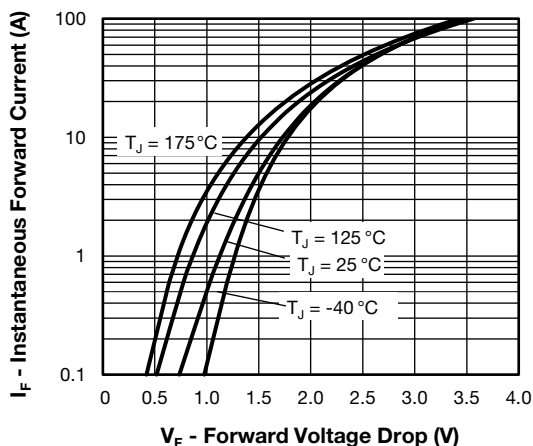


Fig. 1 - Forward Voltage Drop Characteristics

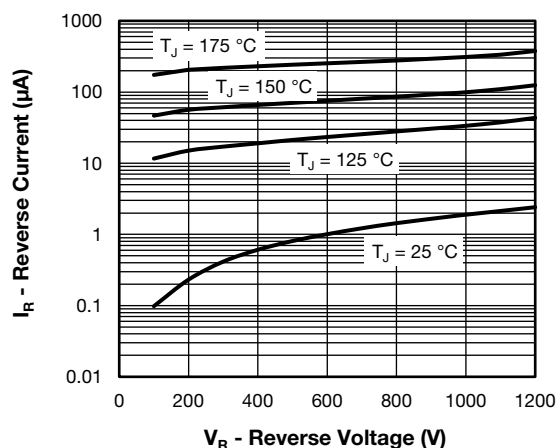


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

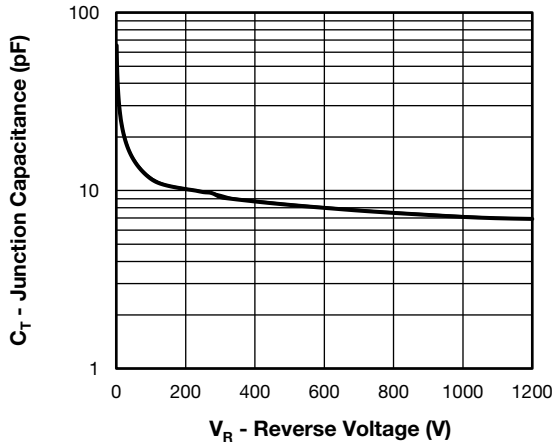


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

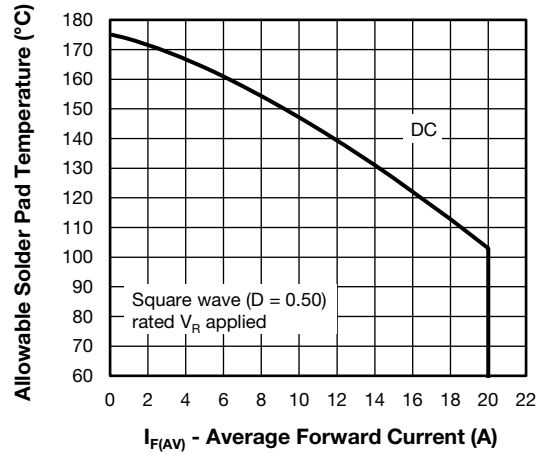


Fig. 4 - Maximum Allowable Case Temperature vs. Average Forward Current

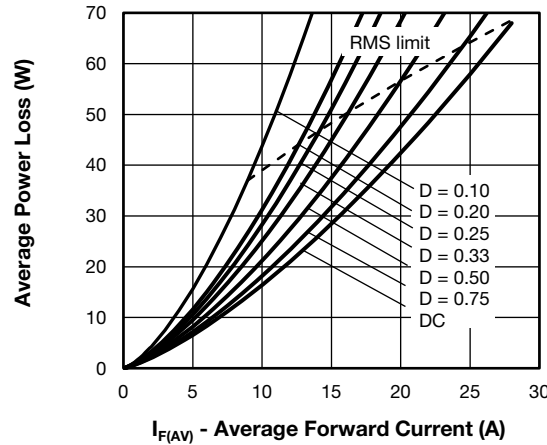


Fig. 5 - Forward Power Loss Characteristics

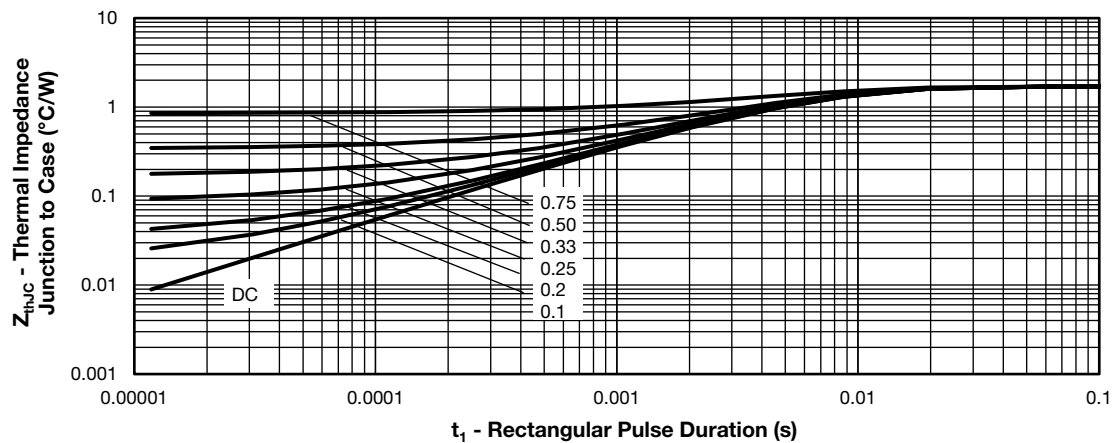
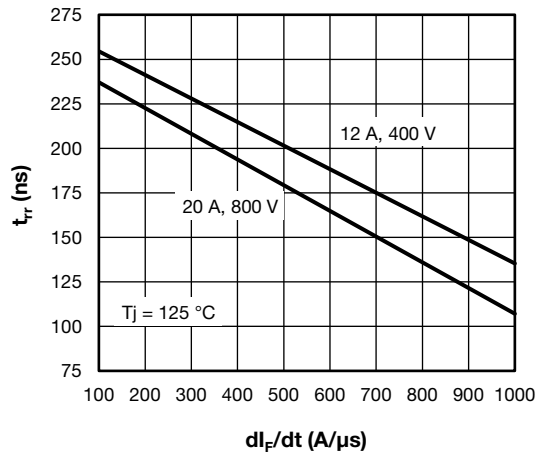
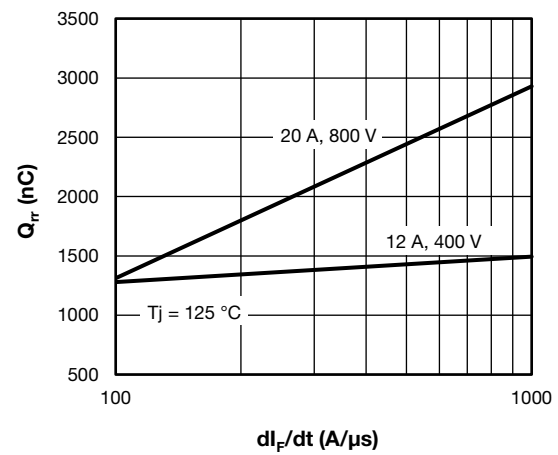
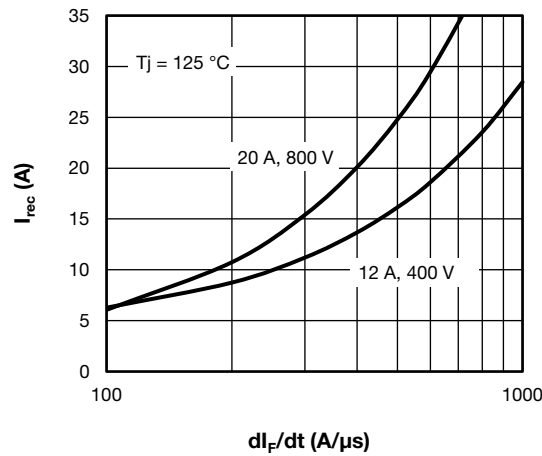


Fig. 6 - Transient Thermal Impedance, Junction to Case


Fig. 7 - Typical Reverse Recovery Time vs. dI_F/dt

Fig. 8 - Typical Stored Charge vs. dI_F/dt

Fig. 9 - Typical Stored Charge vs. dI_F/dt

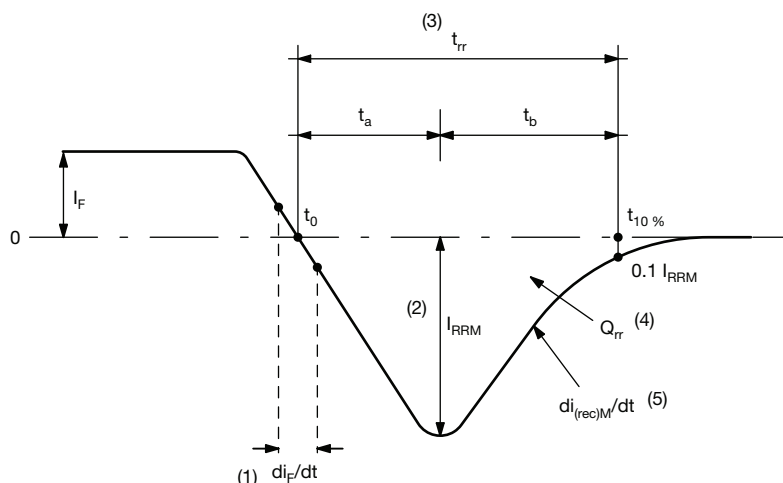


Fig. 10 - Reverse Recovery Waveform and Definitions

Notes

- (1) di_F/dt - rate of change of current through zero crossing
- (2) I_{RRM} - peak reverse recovery current
- (3) t_{rr} - reverse recovery time measured from t_0 , crossing point of negative going I_F , to point $t_{10\%}$, $0.1 I_{RRM}$
- (4) Q_{rr} - area under curve defined by t_0 and $t_{10\%}$

$$Q_{rr} = \int_{t_0}^{t_{10\%}} I(t) dt$$

- (5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}



ORDERING INFORMATION TABLE

Device code	VS-	E	5	T	H	21	12	S2	L	H	M3
	1	2	3	4	5	6	7	8	9	10	11
1	Vishay Semiconductors product										
2	E = single diode										
3	5 = FRED generation 5										
4	Package: T = TO-263 / D ² PAK package										
5	H = hyperfast recovery										
6	Current rating (21 = 20 A)										
7	Voltage rating (12 = 1200 V)										
8	S2 = true 2 pin D ² PAK										
9	None = tube (50 pieces) • L = tape and reel (left oriented, for D ² PAK package) If needed different orientation/packaging, please contact factory										
10	H = AEC-Q101 qualified										
11	Environmental digit: M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free										

ORDERING INFORMATION (Example)

PREFERRED P/N	QUANTITY PER REEL	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-E5TH2112S2LHM3	800	800	13" diameter reel

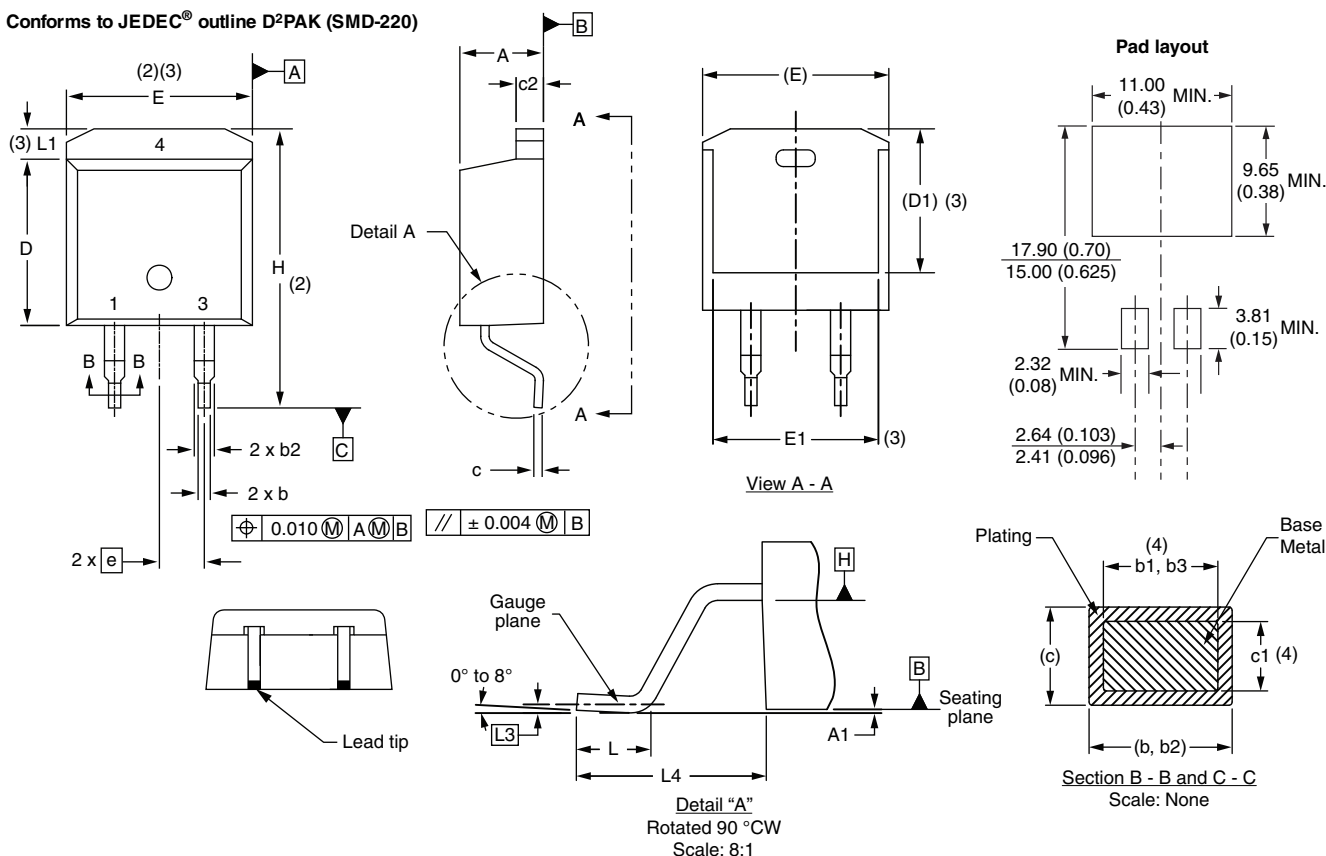
LINKS TO RELATED DOCUMENTS

Dimensions	www.vishay.com/doc?96683
Part marking information	www.vishay.com/doc?96693
Packaging information	www.vishay.com/doc?95032

2L-D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D²PAK (SMD-220)



Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB



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